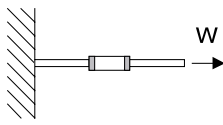
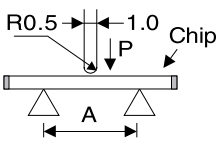


■ PERFORMANCE TESTS

TEST	SPECIFICATION	TEST CONDITION		
Solderability	* More than 90% of the terminal electrode will be covered with fresh solder.	Solder: H63A (Eutectic Solder) Solder Temperature: 230 ± 5°C Flux: Rosin		
Soldering Heat Resistance	* The chip will not crack. * More than 75% of the terminal electrode will be covered with solder.	Solder: H63A (Eutectic Solder) Solder Temperature: 260 ± 5°C Flux: Rosin		
Terminal Strength	* The terminal electrode shall not break and the ferrite will not be damaged. 	TYPE	KGF	Time(sec)
		MLB-160808	0.6	30 ± 5
		MLB-201209		
		MLB-321611	1.0	
		MLB-321616		
		MLB-322513		
		MLB-451616	1.5	
MLB-453215				
Bending Strength	* There will be no mechanical damage. * The ferrite will not be damaged. 	TYPE	A(mm)	KGF
		MLB-160808	1.0	1.0
		MLB-201209	1.4	
		MLB-321611	2.0	2.0
		MLB-321616		
		MLB-322513		
		MLB-451616	2.5	2.5
MLB-453215	2.7			

■ CLIMATIC TESTS

TEST	SPECIFICATION	TEST CONDITION
Thermal Shock (Temperature Cycle)	* Impedance will be within 20% of the initial value.	* Temperature cycles -55°C then +125°C for 30 minutes each. Total Cycles: 100
Humidity Resistance		* Temperature: 60°C * Humidity: 90% RH * Applied Current: Rated Current
High Temperature Resistance		* Temperature: 80°C * Applied Current: Rated Current

**NOTE:** Operating Temperature Range: -55°C TO +125°C

Storage Condition : The temperature should be within 0 ~ 30°C and humidity should be less than 75% RH.

The product should be used within 6 months from the time of delivery.